Notes:
1. Current design is designed for maximum 1.1A constant current output, 100V-200V output voltage range.
2. Dimming circuit is not included.
3. One 2.1" x 1.25" x 0.125" heatsink is applied for D100, D102, Q100.
4. One 2.1" x 1.25" x 0.125" heatsink is applied for Q200, Q203.
5. C901, D902, D903, R901, R902 are add-on parts.
6. Once PSON signal is switched high, it has to remain high until AC source removed.

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Vdd = 15V

Vdd ~ 20V nominal

100V-200V, 1.1A max

Blas Flyback copied for PMP9606

PS on/off control

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